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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(use as many sheets as necessary)**COMPLETE IF KNOWN**

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Filing Date	2/4/98
First Named Inventor	Ritzdorf
Group Art Unit	2823
Examiner Name	Deven M. Collins
Attorney Docket No.	29195.8162US

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U.S. PATENT DOCUMENTS

EXAMINER INITIALS	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
ON	AA	5,972,192		Dubin <i>et al.</i>	10/26/99	
	AB	4,250,004		Miles <i>et al.</i>	2/10/81	
	AC	3,894,918		Corby <i>et al.</i>	7/15/75	
	AD	2,443,599		Allan E. Chester	6/22/48	
	AE	5,605,615		Goolsby <i>et al.</i>	2/25/97	
	AF	6,280,183		Mayur <i>et al.</i>	8/28/01	
ON	AG	6,278,089		Young <i>et al.</i>	8/21/01	

FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T
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OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS

EXAMINER INITIALS	Cite No.	Include: name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.
ON	AH	NGUYEN <i>et al.</i> "Interconnect and Contact Metallization", Eds. H.S. Rathore, G.S. Mathan, C. Plougonven and C.C. Schuckert. PV 97-31, The Electrochemical Society, Inc., Pennington, NJ September 1997
	AI	FOULKE, D.G., in "Gold Plating Technology", Reid, F.H. and Goldic, W., p.67, Electrochemical Publication Limited, British Isles (1996).
	AJ	TOMOV, V., STOYCHEV, D.S., VITANOVA, I.B., "Recovery And Recrystallization Of Electrodeposited Bright Copper Coatings At Room Temperature. II. X-Ray Investigation Of Primary Recrystallization.", <i>Journal of Applied Electrochemistry</i> , 15, 887-894. Chapman and Hall Ltd. (1985).
	AK	RITZDORF, T., GRAHAM, L., JIN, S., MU, C. and FRASER, D., "Self-Annealing of Electrochemically Deposited Copper Films in Advanced Interconnect Applications," Proceedings of the IEEE 1998 International Interconnect Technology Conference, San Francisco, CA (June 1-3, 1998).
	AL	DUBIN, V.M., SHACHAM-DIAMAND, Y., ZHAO, B., VASUDEVA, P.K. and TING, C.H., "Sub-Half Micron Electroless Cu Metallization." Materials Research Society Symposium Proceedings, Vol. 427, San Francisco (1996).
ON	AM	COOK, M. and RICHARDS, T., "The Self-Annealing of Copper," <i>J. Inst. Metals</i> , vol. LXX, pp. 159-173 (1943).